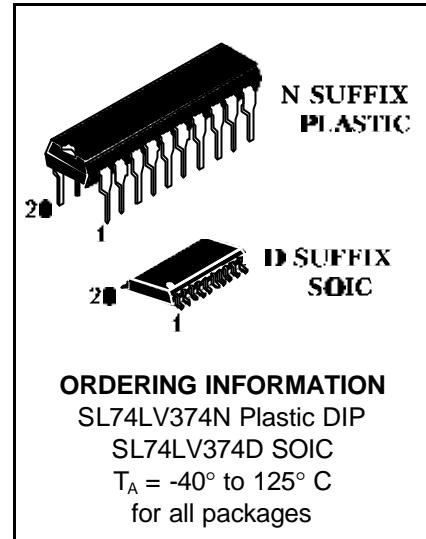


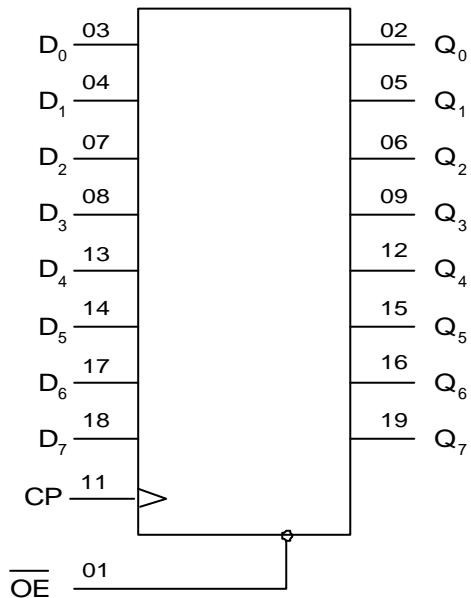
OCTAL D-TIME FLIP-FLOP; POSITIVE EDGE-TRIGGER (3-State)

SL74LV374 are compatible by pinning with SL74HC374 and SL74HCT374 series. Input voltage levels are compatible with standard CMOS levels.

- Output voltage levels are compatible with input levels of CMOS, NMOS and TTL ICs.
- Supply voltage range from 2.0 to 3.2 V
- LOW input current: $1.0 \mu\text{A}$; $0.1 \mu\text{A}$ at $T = 25^\circ\text{C}$
- Output current $8 \mu\text{A}$
- Latch current value not less than $150 \mu\text{A}$ at $T = 125^\circ\text{C}$
- ESD acceptable values: not less than 2000 V as per HBM, and not less than 200 V as per MM

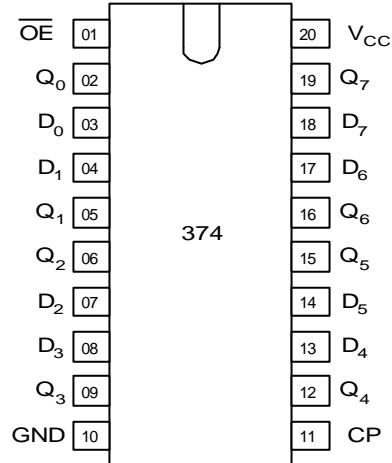


BLOCK DIAGRAM



Pin 20=V_{cc}
Pin 10 = GND

PIN ASSIGNMENT



FUNCTION TABLE

Inputs			Output
\overline{OE}	CP	D _n	Q _n
L	↑	H	H
L	↑	L	L
L	L, H, \overline{L}	X	no change
H	X	X	Z

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ABSOLUTE MAXIMUM RATINGS*

Symbol	Parameter	Rating	Unit
V_{CC}	Supply voltage	-0.5 to +5.0	V
I_{IK}^{*1}	Input diode current	± 20	mA
I_{OK}^{*2}	Output diode current	± 50	mA
I_O^{*3}	Output source or sink current	± 35	mA
I_{CC}	Bus driver outputs	± 70	mA
I_{GND}	Ground current	± 70	mA
P_D	Power dissipation per package, Plastic DIP ^{*4} SOIC ^{*4}	750 500	mW
Tstg	Storage temperature range	-65 to +150	°C

* In absolute maximum ratings modes functioning is not guaranteed. Upon lifting the absolute maximum ratings functioning is guaranteed at the recommended operating conditions.

^{*1} Provide $V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V.

^{*2} Provide $V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V.

^{*3} Provide -0.5 V < $V_O < V_{CC} + 0.5$ V.

^{*4} When operating in the temperature range of 70°C to 125°C power dissipation value decreases

- for Plastic DIP by 12 mW/°C

- for SOIC by 8 mW/°C

RECOMMENDED OPERATING MODES

Symbol	Parameter	Min	Max	Unit
V_{CC}	Supply voltage	1.2	3.6	V
V_{IN}	Input voltage	0	V_{CC}	V
V_{OUT}	Output voltage	0	V_{CC}	V
T_A	Operating ambient temperature range. For all types packages	-40	125	°C
t_{LH}, t_{HL}	Input rise and fall times	$V_{CC} = 1.2$ V $V_{CC} = 2.0$ V $V_{CC} = 3.0$ V $V_{CC} = 3.6$ V	0 700 500 400	ns



System Logic
Semiconductor

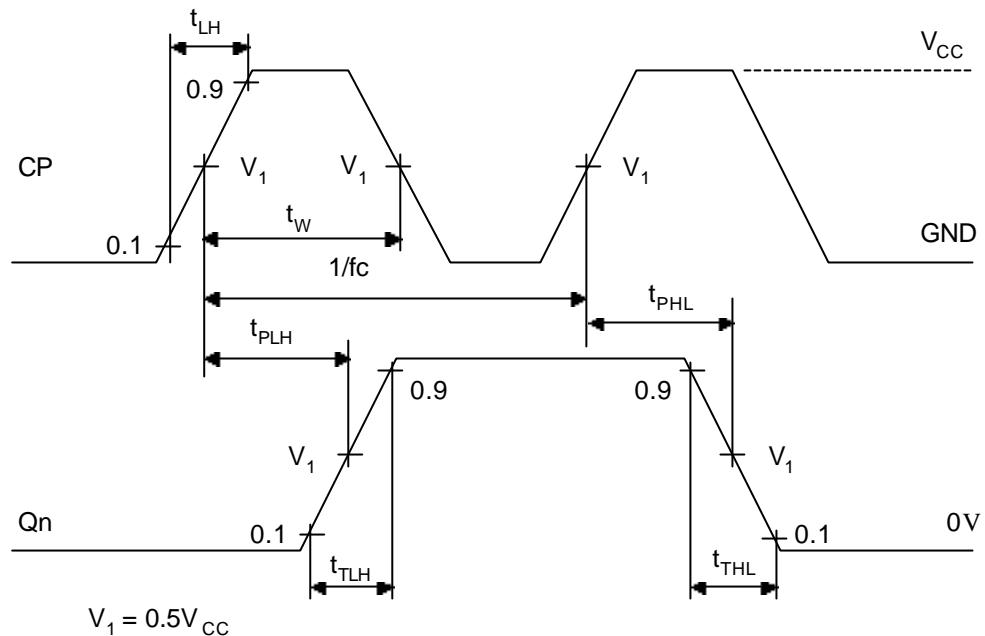
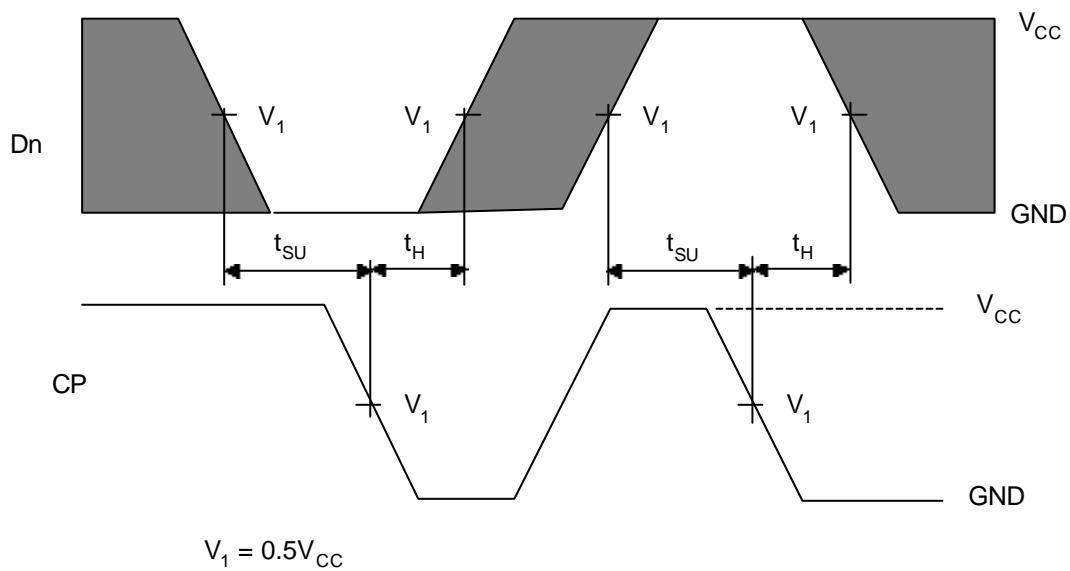
DC CHARACTERISTICS

Symbol	Parameter	Test conditions	V_{CC} , V	Limits						Unit	
				25°C		-40°C to 85°C		125°C			
				min	max	min	max	min	max		
V_{IH}	HIGH level input voltage	$V_O = V_{CC} - 0.1$ V	1.2 2.0 3.0 3.6	0.9 1.4 2.1 2.5	- - - -	0.9 1.4 2.1 2.5	- - - -	0.9 1.4 2.1 2.5	- - - -	V	
V_{IL}	LOW level input voltage	$V_O = 0.1$ V	1.2 2.0 3.0 3.6	- - - -	0.3 0.6 0.9 1.1	- - - -	0.3 0.6 0.9 1.1	- - - -	0.3 0.6 0.9 1.1	V	
V_{OH}	HIGH level output voltage	$V_I = V_{IH}$ or V_{IL} $I_O = -50 \mu A$	1.2 2.0 3.0 3.6	1.1 1.92 2.92 3.52	- - - -	1.0 1.9 2.9 3.5	- - - -	1.0 1.9 2.9 3.5	- - - -	V	
		$V_I = V_{IH}$ or V_{IL} $I_O = -8 m\AA$	3.0	2.48	-	2.34	-	2.20	-	V	
V_{OL}	LOW level output voltage	$V_I = V_{IH}$ or V_{IL} $I_O = 50 \mu A$	1.2 2.0 3.0 3.6	- - - -	0.09 0.09 0.09 0.09	- - - -	0.1 0.1 0.1 0.1	- - - -	0.1 0.1 0.1 0.1	V	
		$V_I = V_{IH}$ or V_{IL} $I_O = 8 m\AA$	3.0	-	0.33	-	0.4	-	0.5	V	
I_I	Input leakage current	$V_I = V_{CC}$ è è è 0 V	3.6	-	± 0.1	-	± 1.0	-	± 1.0	μA	
I_{OZ}	Output OFF-state current	3-state outputs $V_I = V_{IL}$ or V_{IH} $V_O = V_{CC}$ or 0 V	3.6	-	± 0.5	-	± 5	-	± 10	μA	
I_{CC}	Supply current	$V_I = V_{CC}$ or 0 V $I_O = 0 \mu A$	3.6	-	8.0	-	80	-	160	μA	

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AC CHARACTERISTICS ($C_L=50 \text{ pF}$, $t_{LH} = t_{HL} = 6.0 \text{ ns}$)

Symbol	Parameter	Test conditions	V_{CC}, V	Limits						Unit	
				25°C		-40°C to 85°C		125°C			
				min	max	min	max	min	max		
t_{PHL}, t_{PLH} from CP to Qn	Propagation delay	Figure 1	1.2 2.0 3.0	- 45 27	180 - -	- - -	230 56 34	- - -	270 68 41	ns	
t_{PHZ}, t_{PLZ} from OE to Qn	Propagation delay	Figure 3	1.2 2.0 3.0	- - -	160 38 25	- - -	200 57 36	- - -	240 68 43		
t_{PZH}, t_{PZL} from OE to Qn	Propagation delay	Figure 3	1.2 2.0 3.0	- - -	160 38 23	- - -	200 48 29	- - -	240 58 35		
t_{THL}, t_{TLH}	HIGH-to-LOW and LOW-to-HIGH transition time	Figure 1	1.2 2.0 3.0	- - -	75 16 10	- - -	100 20 13	- - -	120 24 15		
t_w	Clock pulse width HIGH or LOW	Figure 1	1.2 2.0 3.0	250 18 11	- - -	350 23 14	- - -	540 28 17	- - -		
t_{SU}	Set-up time Dn to CP	Figure 2	1.2 2.0 3.0	45 13 8	- - -	50 17 10	- - -	100 20 12	- - -		
t_H	Hold time Dn to CP	Figure 2	1.2 2.0 3.0	25 5 5	- - -	25 5 5	- - -	25 5 5	- - -		
f_C	CP maximum pulse frequency	Figure 1	2.0 3.0	- -	27 46	- -	22 37	- -	18 31	MHz	
C_I	Input capacitance		3.0	-	7	-	-	-	-	pF	
C_{PD}	Power dissipation capacitance (per flip-flop)	$V_I = 0 \text{ V or } V_{CC}$	3.0	-	34	-	-	-	-		

**Figure 1 - Time diagram****Figure 2 - Time diagram**

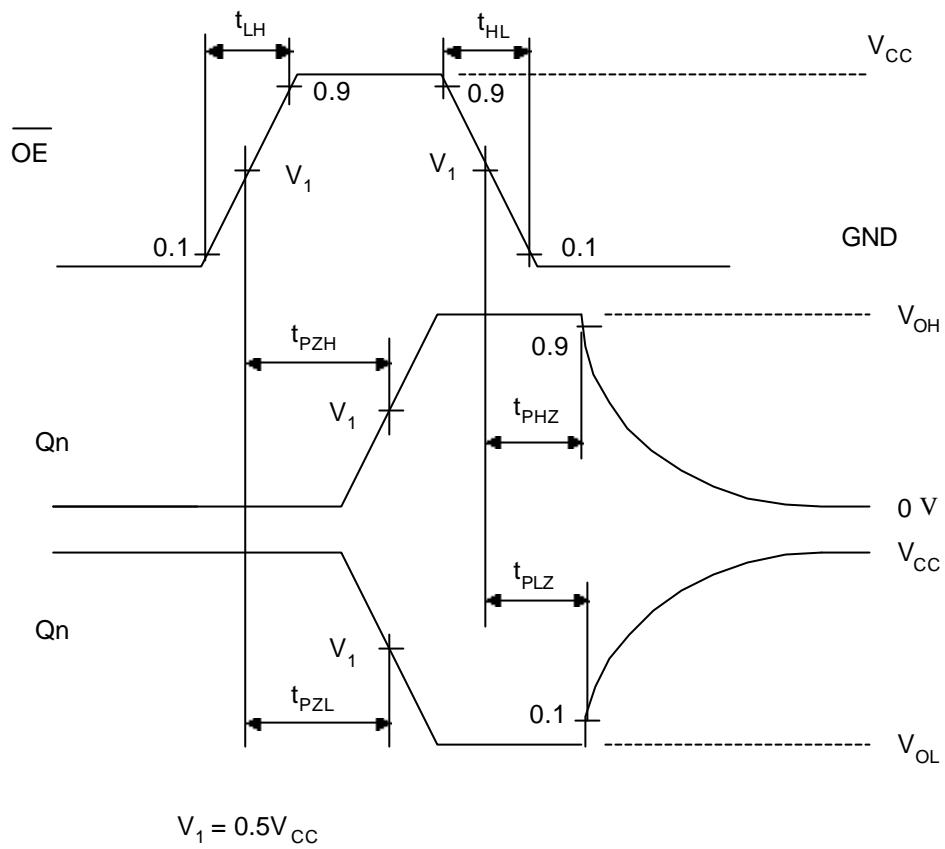
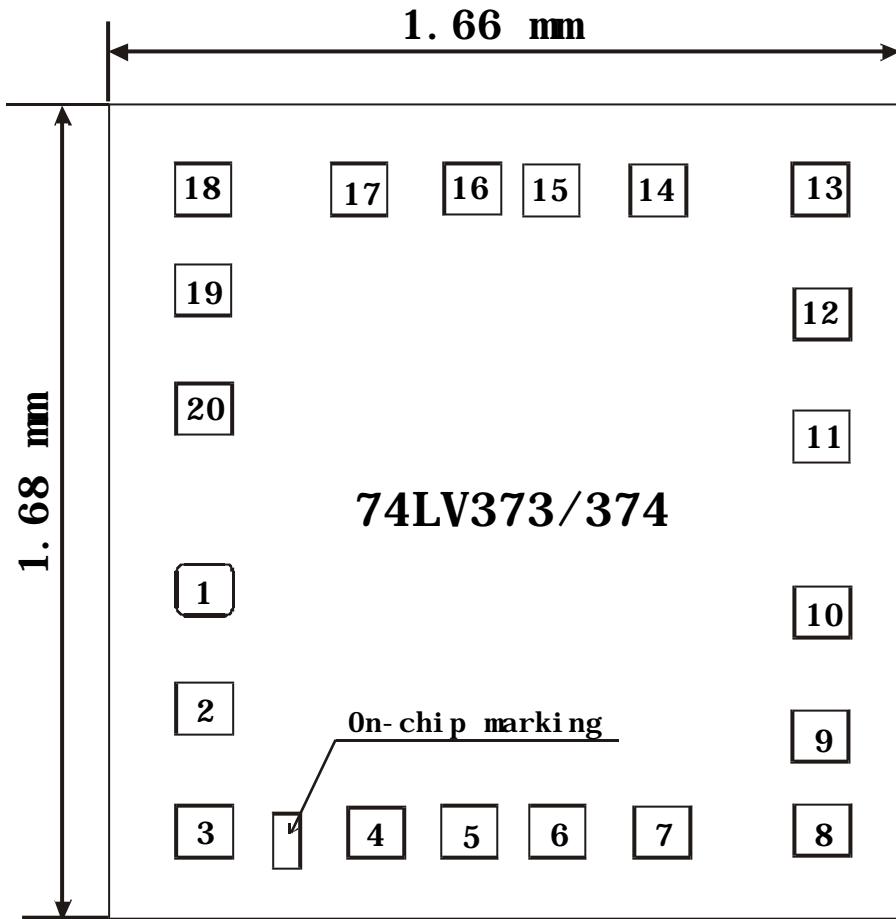


Figure 3 - Time diagram

Drawing of the chip**Pads allocation Table**

Pad number	coordinates (counted from lower left corner), mm		Pad size, mm
	X	Y	
01	0.142	0.628	0.108 x 0.108
02	0.142	0.377	0.108 x 0.108
03	0.142	0.125	0.108 x 0.108
04	0.498	0.125	0.108 x 0.108
05	0.693	0.125	0.108 x 0.108
06	0.871	0.125	0.108 x 0.108
07	1.095	0.125	0.108 x 0.108
08	1.423	0.130	0.108 x 0.108
09	1.423	0.329	0.108 x 0.108
10	1.423	0.587	0.108 x 0.108
11	1.423	0.949	0.108 x 0.108
12	1.423	1.198	0.108 x 0.108
13	1.423	1.447	0.108 x 0.108
14	1.085	1.447	0.108 x 0.108
15	0.868	1.447	0.108 x 0.108
16	0.696	1.447	0.108 x 0.108
17	0.461	1.447	0.108 x 0.108
18	0.142	1.447	0.108 x 0.108
19	0.142	1.245	0.108 x 0.108
20	0.142	0.997	0.108 x 0.108

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